



## FDDI / Fast Ethernet PHYceiver™

### General Description

The **ICS1886** is designed to provide high performance clock recovery and generation for either 32.064 Mb/s, 34.368 Mb/s, 125 Mb/s or 139.264 Mb/s NRZ or NRZI serial data streams. The **ICS1886** is ideally suited for LAN transceiver applications in either European or Japanese communication environments.

The **ICS1886** also operates at the 100Mbit Ethernet frequency of 125 MHz. This is ideal for serial Ethernet data applications where no serial to parallel conversion is required.

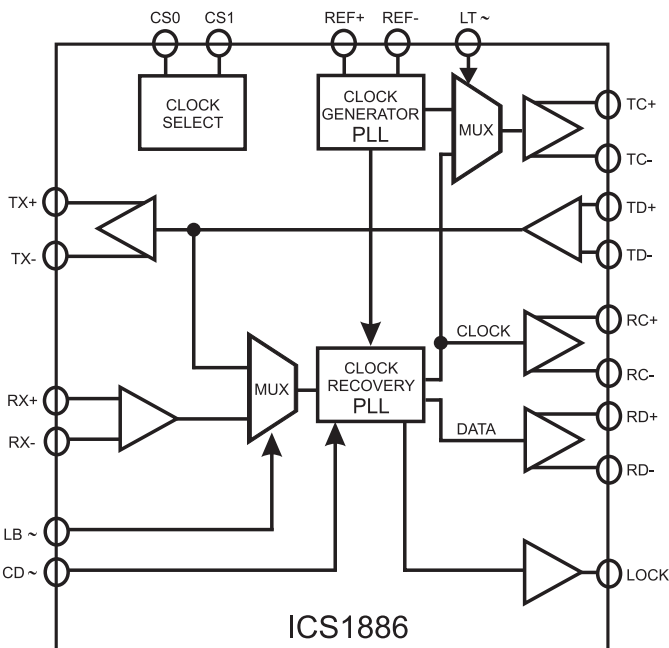
Clock and data recovery is performed on an input serial data stream or the buffered transmit data depending upon the state of the loopback input. A continuous clock source will continue to be present even in the absence of input data. All internal timing is derived from either a low cost crystal or an external clock module.

The **ICS1886** utilizes advanced CMOS phase-locked loop technology which combines high performance and low power at a greatly reduced cost.

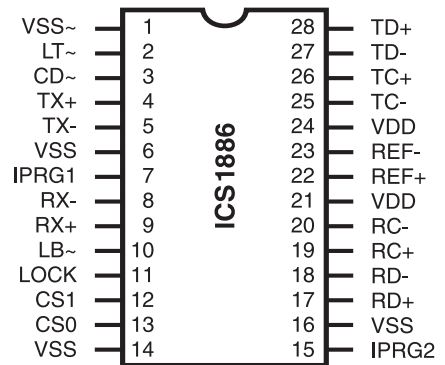
### Features

- Data and clock recovery for: 32.064 Mb/s (Japan) 34.368 Mb/s (Europe - E3) 125 MHz (Ethernet) 139.264 Mb/s (Europe - E4)
- Clock multiplication from either a crystal, differential or single-ended timing source
- Continuous clock in the absence of data
- No external PLL components
- Lock/Loss status indicator output
- Loopback mode for system diagnostics
- Selectable loop timing mode
- PECL drivers with settable sink current

### Block Diagram



### Pin Configuration



**28-Pin SOIC**



**Table 1 - Device Clock Selection**

CS1	CS0	LOOP	INPUT	CLOCK FREQ	MODE	REF FREQ or CRYSTAL
VSS	VSS	VSS	Tx Data	32.064 MHz	Japan	4.008 MHz
VSS	VDD	VSS	Tx Data	34.368 MHz	Europe - E3	4.296 MHz
VDD	VSS	VSS	Tx Data	125.000 MHz	Ethernet	25.000 MHz
VDD	VDD	VSS	Tx Data	139.264 MHz	Europe - E4	17.408 MHz
VSS	VSS	VDD	Rx Data	32.064 MHz	Japan	4.008 MHz
VSS	VDD	VDD	Rx Data	34.368 MHz	Europe - E3	4.296 MHz
VDD	VSS	VDD	Rx Data	125.000MHz	Ehternet	25.000 MHz
VDD	VDD	VDD	Rx Data	139.264 MHz	Europe - E4	17.408 MHz

## Pin Descriptions

PIN NUMBER	PIN NAME	TYPE	DESCRIPTION
1	VSS		Negative supply voltage.
2	LT~		Loop Timing mode select.*
3	CD~		Carrier Detect input.*
4	TX+		Positive Transmit serial data output.
5	TX-		Negative Transmit serial data output.
6	VSS		Negative supply voltage.
7	IPRG1		PECL Output stage current set (TX).
8	RX-		Negative Receive serial data input.
9	RX+		Positive Receive serial data input.
10	LB~		Loop Back mode select.*
11	LOCK		Lock detect output.
12	CS1		Clock select 1 input.
13	CS0		Clock select 0 input.
14	VSS		Negative supply voltage.
15	IPRG2		PECL Output stage current set (TC, RC and RD).
16	VSS		Negative supply voltage.
17	RD+		Positive recovered data output
18	RD-		Negative recovered data output.
19	RC+		Positive recovered clock output.
20	RC-		Negative recovered clock output.
21	VDD		Positive supply voltage.
22	REF+		Positive reference clock/crystal input.
23	REF-		Negative reference clock/crystal input.
24	VDD		Positive supply voltage.
25	TC-		Negative Transmit clock output.
26	TC+		Positive Transmit clock output.
27	TD-		Negative Transmit data input.
28	TD+		Positive Transmit data input.

\* Active Low Input.



### Absolute Maximum Ratings

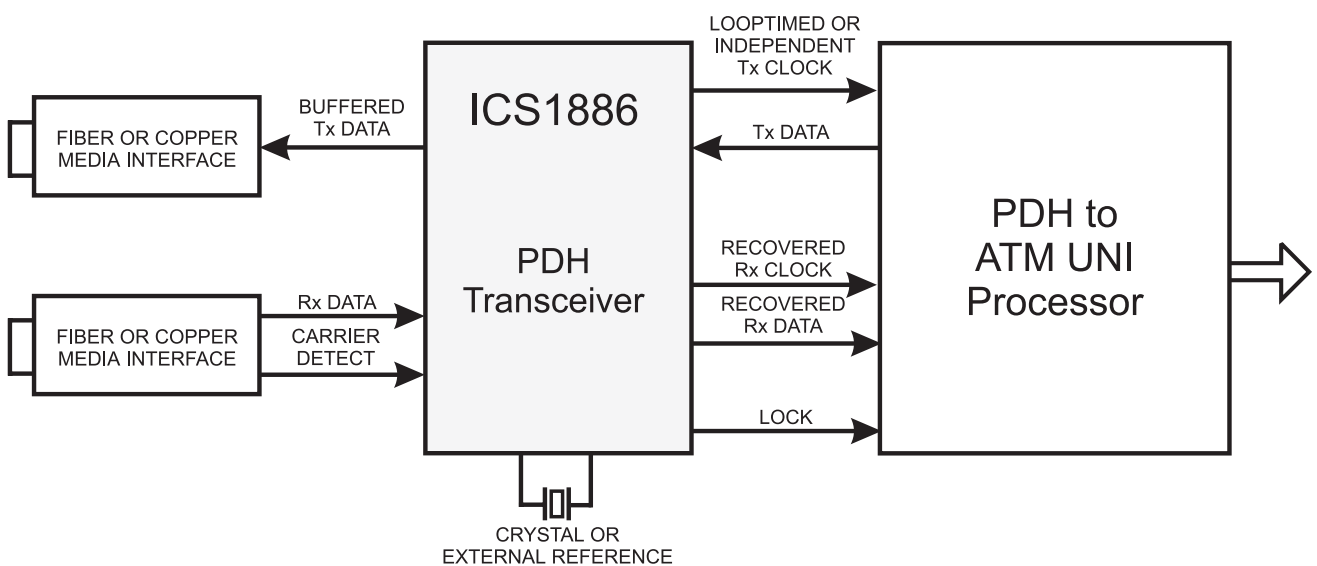
- V<sub>DD</sub> (measured to V<sub>SS</sub>) . . . . . 7.0 V
- Ambient Operating Temperature . . . . . -55°C to +125°C
- Storage Temperature . . . . . -65°C to +150°C
- Junction Temperature . . . . . 175°C
- Soldering Temperature . . . . . 260°C

Stresses above those listed under Absolute Maximum Ratings above may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

### Recommended Operating Conditions

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
Ambient Operating Temp.	T <sub>A</sub>		0	+70	°C
Using a Negative Supply	V <sub>SS</sub>		-4.50	-5.50	V
	V <sub>DD</sub>		0.0	0.0	V
Using a Positive Supply	V <sub>SS</sub>		0.0	0.0	V
	V <sub>DD</sub>		+4.50	+5.50	V

### ICS1886 FDDI / Fast Ethernet Application





## DC Characteristics

$V_{DD} = V_{MIN}$  to  $V_{MAX}$ ,  $V_{SS} = 0V$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS
Supply Current	I <sub>SS</sub>	V <sub>DD</sub> = +5.0V, V <sub>SS</sub> = 0.0V	—	50	mA
<b>ECL Input/Output</b>					
PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS
ECL Input High Voltage	V <sub>IH</sub>		V <sub>DD</sub> -1.16	V <sub>DD</sub> -0.88	V
ECL Input Low Voltage	V <sub>IL</sub>		V <sub>DD</sub> -1.81	V <sub>DD</sub> -1.47	V
ECL Differential Threshold Voltage Range	V <sub>TH</sub>		—	150	mV
ECL Input Common Mode Voltage	V <sub>CM</sub>		1.3	V <sub>DD</sub> - .4	V
ECL Output High Voltage	V <sub>OH</sub>		V <sub>DD</sub> -1.02	—	V
ECL Output Low Voltage	V <sub>OL</sub>		—	V <sub>DD</sub> -1.62	V
<b>TTL Input/Output</b>					
PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS
TTL Input High Voltage	V <sub>IH</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	2.0	—	V
TTL Input Low Voltage	V <sub>IL</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	—	0.8	V
TTL Output High Voltage	V <sub>OH</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	2.7	—	V
TTL Output Low Voltage	V <sub>OL</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	—	0.5	V
TTL Driving CMOS Output High Voltage	V <sub>OH</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	3.68	—	V
TTL Driving CMOS Output Low Voltage	V <sub>OL</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	—	0.4	V
TTL / CMOS Output Sink Current	I <sub>OL</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	—	8	mA
TTL / CMOS Output Source Current	I <sub>OH</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	—	-0.4	mA
<b>REF_IN Input</b>					
PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS
Input High Voltage	V <sub>IH</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	3.5	—	V
Input Low Voltage	V <sub>IL</sub>	V <sub>DD</sub> = 5.0V, V <sub>SS</sub> = 0.0V	—	1.5	V

Note: REF\_IN Input switch point is 50% of VDD.

**AC Characteristics** $V_{DD} = V_{MIN}$  to  $V_{MAX}$ ,  $V_{SS} = 0V$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS
<b>ECL Outputs</b>					
Rise/Fall Time	$t_r, t_f$	15pF Load	1.4	1.7	ns
Recovered clock Duty Cycle	tDC	15pF Load	45	55	%
Output Data Setup	t <sub>sv</sub>	W.R.T. RC at 139.264MHz	2.2	3.3	ns
Output Data Hold	t <sub>hd</sub>	W.R.T. RC at 139.264MHz	3.9	4.5	ns
Transmit Latency	TL	139.264MHz	6	9	ns
Recieve Latency	RL	139.264MHz	1clock+15	1clock+20	ns
<b>Phase-Locked Loop Characteristics</b>					
Lock Acquisition	t <sub>acq</sub>	139.264MHz	—	5	μs
Capture Range		139.264MHz	—	±5	% of center freq.
Receive Jitter Tolerance	t <sub>jt</sub>	139.264MHz	—	.15%	UIp-p
Transmit Clock Stability		139.264MHz 17.408MHz crystal	—	6	ppm



## Input Pin Descriptions

**Transmit Data Input (TD+ and TD-)** For normal operation this differential input is transferred to the TX± output through a PECL buffer. In loopback testing mode, this input is multiplexed to the input of the device clock recovery section.

**Receive Data Input (RX+ and RX-)** The clock recovery and data regenerator from the receive buffer are driven from this PECL input. During loopback testing mode this input is ignored.

**Clock Select (CS0 and CS1)** Selects the operating frequency according to Table 1. Internal pull-up resistors set both inputs high when left unconnected.

**Carrier Detect (CD~)** Active low input which forces the VCO to free run. Upon receipt of a loss of input signal (such as from an optical-to-electrical transducer), the internal phase-lock loop will free-run at the selected operating frequency. Also, when asserted, CD will set the lock output low.

**Loop Timing Mode (LT~)** Active low input which routes the recovered receive clock to the TC± outputs as well as the RC± outputs. Forces the transmit clock to be 'loop-timed' to the system clock derived from the incoming data.

**Loopback Mode (LB~)** Active low input which causes the clock recovery PLL to operate using the transmit TD± input data and ignore the receive RX± data. Utilized for system loopback testing.

**External Crystal or Reference Clock (REF+ and REF-)** This oscillator input can be driven from either a fundamental mode crystal or a stable reference. For either method, the reference frequency is 1/8 the operating frequency. See Table 1 for more information.

**Output Pin Descriptions** Transmit Data Differential ECL (TX+ and TX-) This differential output is buffered TD± data. This output remains active during loopback mode.

**Transmit Clock Differential ECL (TC+ and TC-)** Differential output clock used by the PDH/ATM processor for clocking out transmit data. This clock can be derived from either an independent clock source or from the recovered data clock (system loop time mode).

**Receive Data Differential ECL (RD+ and RD-)** The regenerated differential data derived from the serial data input. In loopback mode this data is regenerated from the transmit data input (TD±). This data is phase-aligned with the negative edge of the RC clock output.

**Receive Clock Differential ECL (RC+ and RC-)** The differential clock recovered with the internal clock recovery PLL. In loopback mode this clock is recovered from the transmit data (TD±) input. This clock is phase-aligned with the RD data output.

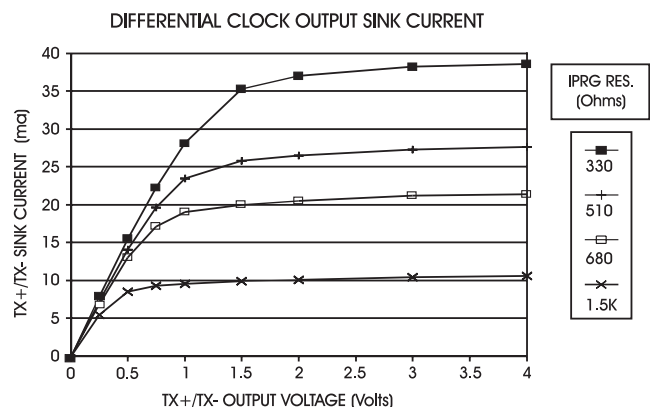
**Lock/Loss Detect (LOCK)** Set high when the clock recovery PLL has locked onto the incoming data. Set low when there is no incoming data, which in turn causes the PLL to free-run. This signal can be used to indicate or 'alarm' the next receive stage that the incoming serial data has stopped.

## Output Description

The differential output drivers are current mode and are designed to drive resistive terminations in a complementary fashion. The outputs are current-sinking only, with the amount of sink current programmable via the IPRGx pins. The sink current is equal to four times the IPRGx current. For most applications, a resistor from VDD to IPRGx will set the current to the necessary precision. IPRG1 supplies the current mirror for the TX± output. IPRG2 supplies the current mirrors for the RD±, RC± and TC± outputs.

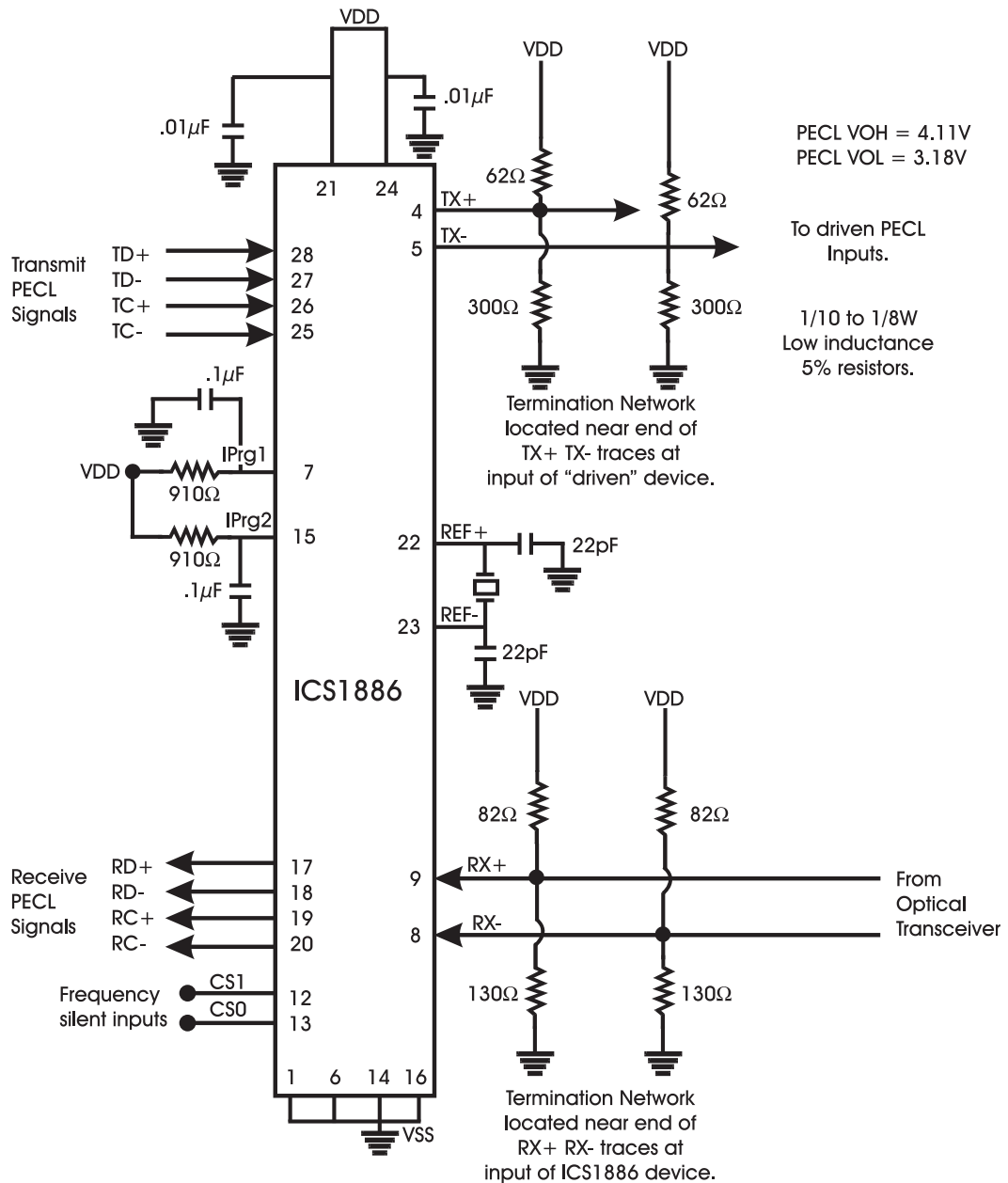
The differential PECL output pins are incapable of sourcing current, so VOH must be set by the ratios of the termination resistors for each of these lines. R1 is a pull-up resistor connected from the PECL output to VSS. R1 and R2 are electrically in parallel from an AC stand point. If we pick a target impedance of 50Ω for our transmission line impedance, a value of 62Ω for R1 and a value of 300Ω for R2 would yield a Thevenin equivalent characteristic impedance of 50Ω and a VOH value of VDD-0.88 volts, compatible with PECL circuits.

To set a value for VOL, we must determine a value for Iprg that will cause the output FET's to sink an appropriate current. We desire VOL to be VDD-1.81 or greater. Setting up a sink current of 19 milliamperes would guarantee this through our output terminating resistors. As this is controlled by a 4/1 current mirror, 4.75mA into Iprg should set this current properly. An 910Ω resistor from VDD to Iprg should work fine.





### ICS1886 PECL Termination for 50W Transmission Lines





The current **ICS1886** device provides a single TTL-compatible input, carrier detect (CD~). When carrier detect is asserted, the ICS1886 locks to the incoming receive data. When carrier detect is deasserted, or if carrier detect is asserted and no data is present on the receive inputs, the PLL will free run and continue to provide RXCLK at the nominal 25 MHz frequency. This provides a continuous Receive clock source, even if CD~ is always tied to ground.

If a true signal detect is required by a chip that connects to the **ICS1886**, a simple, low cost PECL to CMOS converter can be used. The following circuits implement this function:

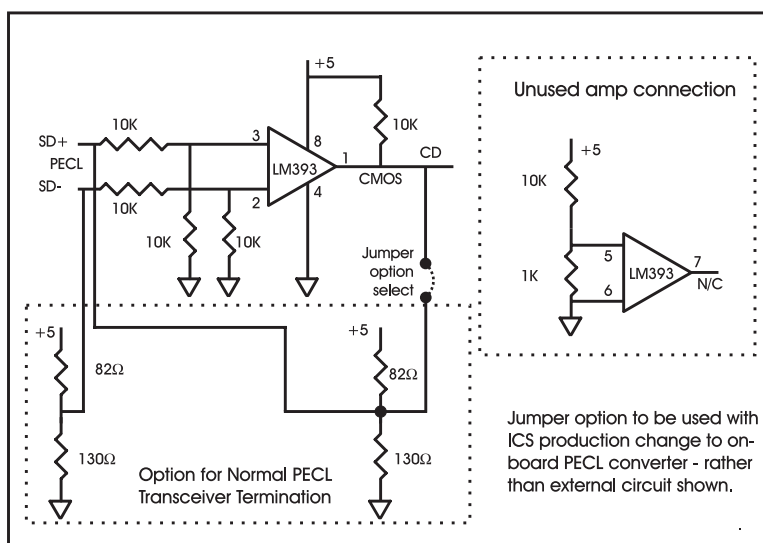
These circuits provide PECL to CMOS conversion for less than \$0.80 in single unit quantities. Note that the LM393 has two amplifiers, so the unused one is tied inactive.

A running production change will be made to the **ICS1886** to change the CD~ input to PECL. Therefore, boards should be laid out with a direct normal PECL termination connection stuffing option. This allows either version of the part to be used by stuffing one of two sets of external components. A version of this circuit is shown in the diagram above.

## CD PECL Input: Board Layout Options

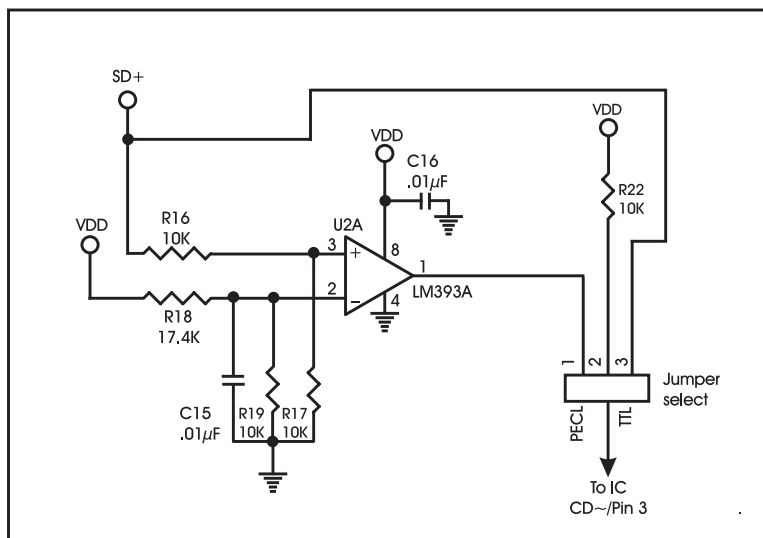
### Option 1

#### Differential PECL to CMOS Conversion Circuit



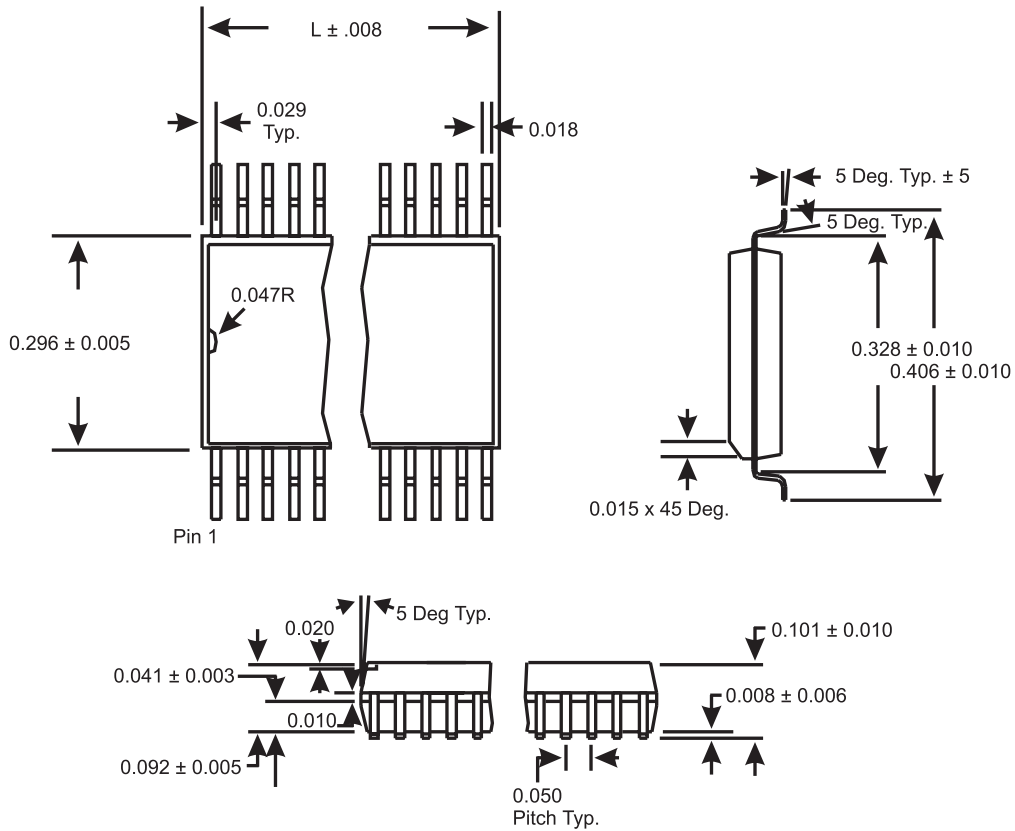
### Option 2

#### Single-Ended PECL to CMOS Conversion Circuit









**SOIC PACKAGE**

LEAD COUNT	28L
DIMENSION L	0.704

**Ordering Information**

**ICS1886M**

Example:

**ICS XXXX M**

